Information & Control North America TC Chapter

Meeting Summary and Minutes

North America Winter Meetings

Wednesday, February 11, 2026

9:00-12:00, 1:00-4:00 PM Pacific

TC Chapter Announcements

Next TC Chapter Meeting

ASMC

Wednesday, May 13, 2026

9:00-12:00, 1:00-4:00 PM Eastern

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: James Moyne (Applied Materials / University of Michigan), Brian Rubow (Cimetrix by PDF Solutions), Albert Fuchigami (PEER Group)
SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
Agileo Automation	*Golra*	*Fahad*	Micron	*Cicero*	*Jason*
Applied Materials	*Matthew*	*Rony David*	Micron	*Schwarthoff*	*Hubert*
Cimetrix by PDF Solutions	*Rubow*	*Brian*	PEER Group	*Fuchigami*	*Albert*
Cimetrix by PDF Solutions	*Ryu*	*Ian*	SCREEN	*Stokes*	*Harold*
Cimetrix by PDF Solutions	*Weber*	*Alan*	SCREEN	*Nishimura*	*Takayuki*
Cimetrix by PDF Solutions	*Tracey*	*Tami*	SCREEN	*Futatsugi*	*Tetsuya*
Hitachi High-Tech	*Toyoshima*	*Yuko*	Self	*Neuber*	*Andreas*
Intel	*Maloney*	*Chris*	Self	*Howard*	*Richard*
Intel	*Bond*	*Ryan*	SEMI	*Sun*	*Michelle*
Global Foundries	*Downey*	*Jack*	TEL	*Mashiro*	*Supika*
Kokusai Electric	*Matsuda*	*Mitsuhiro*	TEL	*Kazutaka*	*Yamaguchi*
Onto Innovation	*McLane*	*Adam*	TEL	*Fujimori*	*Yuta*
Onto Innovation	*Chase*	*Sonia*			

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
CDS Task Force	Ryan Bond (Intel)	Mike Tanori (Intel)

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7345A	Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking	
LI-1	Report Batch Loading and Unloading	**Failed**
LI-2	Correct Well-Known Names	**Passed** as balloted
7419	Line-Item Revision to SEMI E120-1225 Specification for the Common Equipment Model (CEM), SEMI E120.2-1225 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1225 Specification for Equipment Self Description (EqSD), SEMI E125.2-1225 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1225 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1225 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1225 Specification for Data Collection Management, SEMI E134.2-1225 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1225 Specification for Protocol Buffers Common Components	
LI-1	Rework SEMI E125 metadata to better work with multiple SECS identifiers	**Failed**
LI-2	Add new SEMI E132 SecurityCertificateChanged notification message	**Passed** with editorial changes
LI-3	Update issues raised by TF members	**Failed**
7420	Line Item Revision to SEMI E190.1-1124 – Specification for Common Data for Etch Components	
LI-1	Add Level 2 and 3 categories of etch information; and expand Definitions section to cover any new terms introduced in these categories.	**Failed**
LI-2	Add Related Information section to explain etch processing theory of operation	**Failed**
7422	Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata	**Failed**
7425	Line-Item Revision to SEMI E116-0324 Specification for Equipment Performance Tracking	
LI-1	Establish Unique Well-Known Names	**Passed** as balloted
7428	Revision to Add a New Subordinate Standard: Specification for Secure High-Speed SECS Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services	**Failed**

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
R6743C	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment	**Passed**	

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
7422	SNARF	DDA	Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7447	SNARF	GEM 300 TF	Line-Item Revision to SEMI E40-0324 Specification for Processing Management
7448	SNARF	ESEC TF	Line-Item Revision to SEMI E175-1116 Specification for Subsystem Energy Saving Mode Communication (SESMC)
7449	SNARF	GUI TF	Line-Item Revision to SEMI E95-1101 (Reapproved 0307) Specification for Human Interface for Semiconductor Manufacturing Equipment
7450	SNARF	GEM 300 TF	Reapproval of SEMI E173-0721 Specification for XML SECS-II Message Notation (SMN)
7451	SNARF	Sensor Bus TF	Reapproval of SEMI E54.11-0316 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
7452	SNARF	Sensor Bus TF	Reapproval of SEMI E54.3-0698 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7070	Cycle 4-2026	EDP TF	Revision to Add a New Subordinate Standard: Specification for Common Data for Vacuum Components to Specification for Equipment Data Publication
7187	Cycle 4-2026	ESEC TF	Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
7345B	Cycle 4-2026	GEM300 TF	Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking
7380A	Cycle 4-2026	ABFI TF	Line Item Revision to SEMI E142-0225 - Specification for Substrate Mapping, SEMI E142.1-0225 — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 (0225) — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) — Specification for Web Services for Substrate Mapping,

Table 8 Authorized Ballots

#	When	TF	Details
			SEMI E142.4-1022 (0225) — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer
7381	Cycle 4-2026	ABFI TF	Revision to Add a New Subordinate Standard: Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125: Specification for Substrate Mapping
7419A	Cycle 4-2026	DDA TF	Line-Item Revision to SEMI E120-1225 Specification for the Common Equipment Model (CEM), SEMI E120.2-1225 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1225 Specification for Equipment Self Description (EqSD), SEMI E125.2-1225 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1225 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1225 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1225 Specification for Data Collection Management, SEMI E134.2-1225 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1225 Specification for Protocol Buffers Common Components
7420A	Cycle 4-2026	EDP TF	Line Item Revision to SEMI E190.1-1124 – Specification for Common Data for Etch Components
7422A	Cycle 4-2026	DDA TF	Revision to SEMI E164-1224 Specification for EDA Common Metadata And To Add New Subordinate Standards Specification for GEM Common EDA Metadata, Sensor Bus TF Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata
7426	Cycle 4-2026	CDS TF	Line-Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7427	Cycle 4-2026	GEM300 TF	Line Item Revision to SEMI E172-0725 Specification for SECS Equipment Data Dictionary (SEDD)
7428A	Cycle 4-2026	GEM300 TF	Revision to Add a New Subordinate Standard: Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services
7447	Cycle 4-2026	GEM300 TF	Line Item Revision to SEMI E40-0324 Specification for Processing Management
7448	Cycle 4-2026	GEM300 TF	Reapproval of SEMI E173-0721 Specification for XML SECS-II Message Notation (SMN)
7449	Cycle 4-2026	ESEC TF	Line Item Revision to SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)
7451	Cycle 4-2026	Sensor Bus TF	Reapproval of SEMI E54.11-0316 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
7452	Cycle 4-2026	Sensor Bus TF	Reapproval of SEMI E54.3-0698 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device
7456	Cycle 4-2026	EDP TF	Revision to Add a New Subordinate Standard: Specification for Common Data for Deposition Components to Specification for Equipment Data Publication
7457	Cycle 4-2026	EDP TF	Revision to Add a New Subordinate Standard: Specification for Common Data for Ion Implant Components to Specification for Equipment Data Publication

Table 9 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 10 SNARF(s) Cancelled

#	TF	Title
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
1	Michelle Sun (SEMI)	Add Digital Twins to the I&C TC Meeting agenda
2	Albert Fuchigami (PEER Group), Brian Rubow (Cimetrix by PDF Solutions)	Review DDA SNARFs
3	Michelle Sun (SEMI)	Avoid being conflict with SEMICON Korea for next SEMICON Winter meetings
4	Michelle Sun (SEMI)	Ask if Sensor Bus authors would like to lead task force

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
1	Albert Fuchigami (PEER Group)	Investigate EDA patents, which may be expiring soon - **COMPLETE**
2	Michelle Sun (SEMI)	Obtain LOA for SEMI E54.18 - **WIP**

1 Welcome, Reminders, and Introductions

Albert Fuchigami (PEER Group) called the meeting to order at 9:07. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	By: Chris Maloney / Intel Corporation Second: Fahad Golra / Agileo Automation
Discussion:	None
Vote:	8-Y 0-N

Attachment: IC-Minutes-Oct-2025

3 Liaison Reports

3.1 *Information & Control Japan TC Chapter*

Nishimura Takayuki (SCREEN) reported for the Information & Control Japan TC Chapter. Of note:

- Meeting Information
  - Tuesday, October 21, 2025, 9:00am – 12:00pm [JST] *The time before last
  - SEMI Japan office Room 1 + OVTCCM [Hybrid]
  - Friday, December 19, 2025, 1:30pm - 4:30pm [JST]
  - Room 905, East 9F, TFT Building in conjunction with SEMICON Japan 2025 + OVTCCM [Hybrid]
- Next Meeting
  - Friday, April 10, 2026, 9:30am – 12:00pm [JST]
  - SEMI Japan office + OVTCCM [Hybrid]
- Leadership Changes
  - Maintenance Robot Communication (MRC) Task Force
    - New Leader: Tadashi Mochizuki - Tokyo Electron Limited
  - Task Forces
    - New Task Force: Maintenance Robot Communication (MRC) Task Force
    - 'JA I&C Maintenance Task Force' renamed to 'Maintenance Task Force'
- Ballot Results
  - 7354, Line Item Revision to SEMI E170-0520: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS) and SEMI E170.1-0520: SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (**LI 1-4 Passed**)
- Authorized Activities
  - Japan I&C Maintenance Task Force – Revised Name, Charter and Scope
  - New Task Force: Maintenance Robot Communication (MRC) Task Force
  - GEM300 Task Force - Revised Name, Charter and Scope
  - New SNARF: 7440, Revision of E169-0623 Guide for Equipment Information System Security
- Other Activities
  - R7354, SEMI E170.1-0520 SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM

Attachment: JA_I&C_Liaison_2026_Jan_rev4

3.2 *Information & Control Korea TC Chapter*

Michelle Sun (SEMI) reported for the Information & Control Korea TC Chapter. Of note:

Meeting Information

- Last Meeting
  - November 27, 2025
  - SEMI Korea, Seoul (hybrid)
- Next Meeting
  - April 23, 2026
  - SEMI Korea, Seoul (hybrid)
- Task Force Highlights
  - ABFI TF
    - Hold an internal seminar on packaging automation trends on September 4.
    - As most members are frontend engineers, the seminar is intended to help them understand backend automation and to discuss plans and potential items for backend automation standards.

Attachment: Liaison report_KR_InC_Dec2025

3.3 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

2026 Calendar of Events

Event Name	Event Details
SEMICON KOREA	Feb 11-13 Seoul, Korea
SEMICON CHINA	March 25-27 Shanghai, China
SEMIEXPO HEARTLAND	April 29-30 Detroit, Michigan
SEMICON SOUTHEAST ASIA	May 05-07 Kuala Lumpur, Malaysia
SEMICON TAIWAN	Sept 2-4 Taipei
SEMICON® INDIA	Sept 17-19 New Delhi

SEMICON West 2026-2030

- 2026—October 13-15 | Moscone Center | San Francisco, CA
- 2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ
- 2028—October 10-12 | Moscone Center | San Francisco, CA
- 2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ
- 2030—October 29-31 | Moscone Center | San Francisco, CA

Upcoming NA Meetings 2026

- NA Winter Meeting – Feb 9-12 via Web Conference
- NA Spring Meeting – May 11-14 at Albany, NY
- SEMICON West Meeting - October 12-15 at San Francisco, CA

ASMC Meeting Registration & Sponsorship

- Registration
    - Standards Meetings Registration
        - https://bit.ly/Standards_ASMC_2026
- Hotel Reservation
    - Hotel Link: https://www.hilton.com/en/attend-my-event/asmc-conference-may-2026/
    - Call 1(800) Hiltons reservation line and provide the code "4ASMC"
    - Deadline: Tuesday, April 21
- Sponsorship needed
    - Event Logistics (e.g., Catering, Coffee breaks, AV)
    - Please contact staff for more info.
- SEMI Advanced Semiconductor Manufacturing Conference (ASMC)
    - SEMI's international technical conference to discuss solutions that improve the collective manufacturing expertise of the semiconductor industry.
    - Provides a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.
- 14 New SEMI Standards Published in 2025
    - SEMI E192 – Guide for Equipment Adoption Criteria for GEM and GEM-related Standards
    - SEMI D87 – Test Method for Response Time Evaluation of Displays with Variable Refresh Rate
    - SEMI PV102 – Guide for Tube PECVD Graphite Boat Materials for Solar Cell Production
    - SEMI F122 – Guide for Facilities Data Package for Manufacturing Equipment Installation and Building Information Modeling
    - SEMI D88 – Specification for Electrostatic Properties of FPD Photomasks and Blanks Package
    - SEMI MS15 – Guide to MEMS Manufacturing Readiness Levels
    - SEMI E193 – Specification for 300 mm Film Frame FOUP (FFF)
    - SEMI M94 – Specification for Silicon Carbide Engineered Substrates
    - SEMI E194 – Guide to Using a Liquid Particle Counter to Assess Particulate Surface Contamination on Critical Chamber Components and Coupons
    - SEMI E195 – Test Method Using Adhesive Replacement Substrates to Assess Particulate Surface Contamination on Critical Chamber Components
    - SEMI E196 – Guide for Equipment Edge Data Governance
    - SEMI M95 – Test Method for Net Carrier Density and Resistivity of Silicon Epitaxial Layer by Capacitance–Voltage Measurements with an Evaporated Metal Schottky Diode
    - SEMI T26 – Specification for Electronic Supply Chain Traceability Using Distributed Ledger Technology
    - SEMI T27 – Specification for Traceability Identification Label of Component Parts
- Educational Courses under Development
    - {Subfab} Intro to Sub-fab Course
        - Objective: Gain a comprehensive understanding of SubFAB operations, including system components, facility layouts, environmental and sustainability considerations, organizational structure, safety and maintenance best practices, and incident-response preparedness within the semiconductor manufacturing ecosystem.
        - Course Date: Early 2026 (2 sessions, EU & Asia friendly)
    - Status: Under development
    - Other courses being considered: SECS/GEM, Seals, Cybersecurity

Attachment: I&C_Staff_HQ Report Feb 2026 v3

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7345A, Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking

4.1.1 Line Item #1: Report Batch Loading and Unloading

Reject Name:	Fahad Golra / Agileo
Reference:	8.4.3 and 8.4.4
Negative:	8.4.3 & 8.4.4 say "Some data in Table 19 ….", however the title of the table is "Variables Required for Batch Location Object and Batch Object State Model Transitions". Either all the lister variables are required, or some of them. If only some of them are required, which ones? Not explicit. Also in 8.8, it is stated that some data items defined in Table 19 are required to …. • BatchLoadingState in Batch object and in BatchLocation object can have different names to avoid confusion. • The value of BatchLoadingState will always be "LOADED" for transition 1 and "EMPTY" for transition 2. So apparently, no benefit of linking these data variables to the collection event. • Transferring a Batch from one Batch Location to another can create problems.
Motion:	Negative is related and persuasive
By / 2nd:	By: Chris Maloney / Intel Corporation Second: Brian Rubow / Cimetrix by PDF Solutions
Discussion:	None
Vote:	11-Y 0-N

Motion:	Line item(s) [1] failed TC Chapter review and will be returned to the TF for rework. Line item(s) [2] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	By: Chris Maloney / Intel Corporation Second: Fahad Golra / Agileo Automation
Discussion:	None
Vote:	8-Y 0-N

Attachment: AR – 7345A

4.2 Document #7419, Line-Item Revision to

SEMI E120-1225 Specification for the Common Equipment Model (CEM),
SEMI E120.2-1225 Specification for Protocol Buffers for Common Equipment Model (CEM),
SEMI E125-1225 Specification for Equipment Self Description (EqSD),
SEMI E125.2-1225 Specification for Protocol Buffers for Equipment Self Description (EqSD),
SEMI E132-1225 Specification for Equipment Client Authentication and Authorization,
SEMI E132.2-1225 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA),
SEMI E134-1225 Specification for Data Collection Management,
SEMI E134.2-1225 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1225 Specification for Protocol Buffers Common Components

4.2.1 Line Item #1: Rework SEMI E125 metadata to better work with multiple SECS identifiers

Reference:	N/A
Reject Name:	Albert Fuchigami / PEER Group
Negative:	Adding SECSVarRefType directly to EquipmentParameterReferenceType introduces several challenges across all messages that use it: •**Duplication:** Every message that references EquipmentParameterReferenceType (such as StateMachineInstanceEventType, SimpleEventInstanceType, AttributeType, UnitConfigType, ExceptionInstanceType, etc.) must now also carry SECSVarRefType details, leading to repeated configuration throughout the model.

•**Inconsistency Risk:** If SECS variable information is updated in one place but not others, it can result in mismatched or outdated SECS mappings across different parts of the system.

•**Maintenance Overhead:** Any schema or mapping change to SECSVarRefType requires updates in all messages and instances where EquipmentParameterReferenceType is used, increasing the maintenance burden.

•**Model Complexity:** The semantic meaning of EquipmentParameterReferenceType becomes overloaded, as it now represents both a parameter reference and its SECS mapping, making the model harder to understand and evolve.

•**Scalability Issues:** As the model grows, the number of places where SECSVarRefType must be managed increases, compounding all the above issues.

Motion: Negative is related and persuasive

By / 2nd: By: Albert Fuchigami / PEER Group Inc.
Second: Fahad Golra / Agileo Automation

Discussion: None

Vote: 11-Y 0-N

4.2.2 Line Item #3: Update issues raised by TF members

Reference: N/A

Reject Name: Mitsuhiro Matsuda / Kokusai Electric

Negative: The addition of "minReportingInterval <= maxReportingInterval" to the definition of maxReportingInterval is proposed.

I understand this to mean that minReportingInterval shall be less than or equal to maxReportingInterval.

However, expressing this constraint only as an equation is not sufficiently clear.

Since this can be addressed as an Editorial Change, I believe it should be revised to include an explicit textual description.

Motion: Negative is related and persuasive

By / 2nd: By: Albert Fuchigami / PEER Group Inc.
Second: Fahad Golra / Agileo Automation

Discussion: None

Vote: 12-Y 0-N

Motion: Line item(s) [1] failed TC Chapter review and will be returned to the TF for rework.
Line item(s) [2] passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.
Line item(s) [3] failed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.

By / 2nd: By: Chris Maloney / Intel Corporation
Second: Fahad Golra / Agileo Automation

Discussion: None

Vote: 8-Y 0-N

Attachment: AR - 7419

4.3 Document #7420, Line Item Revision to SEMI E190.1-1124 – Specification for Common Data for Etch Components

4.3.1 Line Item #1: Add Level 2 and 3 categories of etch information; and expand Definitions section to cover any new terms introduced in these categories.

Reject Name: Matsuda Mitsuhiro / Kokusai Electric

Reference: N/A

Negative: I found several differences between the published version of E190.1-1124 and the text included in Document 7420, such as the addition of E188 to Section 4, the addition of definitions in Section 5.2, reordering of items in Table 3, and formatting changes in Table 5 (it should be 4) for the Etch EDP Level 2 Categories.

Since these items are not within the scope of this ballot, they will not be revised and will remain as published in E190.1-1124.

If the modification, such as the addition of definitions, is mandatory for this line item, you shall fail this line item and reballot it.

Regarding the table formatting issues, I believe they can be corrected through Editorial Changes.

Motion: Negative is related and persuasive

By / 2nd: By: Alan Weber / Cimetrix by PDF Solutions
Second: Chris Maloney / Intel Corporation

Discussion: None

Vote: 11-Y 0-N

4.3.2 Line Item #2: Add Related Information section to explain etch processing theory of operation

Reject Name: Tadashi Mochizuki / TEL

Reference: N/A

Negative: R1-5 The Etch Component/Process Glossary is intended to be defined, but it currently has no content

Motion: Negative is related and persuasive

By / 2nd: By: Alan Weber / Cimetrix by PDF Solutions
Second: Chris Maloney / Intel Corporation

Discussion: None

Vote: 12-Y 0-N

Motion: Line item(s) [1], [2] failed TC Chapter review and will be returned to the TF for rework

By / 2nd: By: Alan Weber / Cimetrix by PDF Solutions
Second: Brian Rubow / Cimetrix by PDF Solutions

Discussion: None

Vote: 11-Y 0-N

4.4 Document #7422, Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards, Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata

Reject Name: Mitsuhiro Matsuda / Kokusai Electric

Negative: Some Requirement Identifications in the current Letter Ballot are the same as those in the published E.164-0414 (Reapproved 0721), even though the corresponding requirement text has changed. As a result, it is unclear whether these changes are intended as revisions to existing requirements or as new requirements.

Although the document represents a complete rewrite, it remains an E164 specification, and the Requirement Identifiers therefore need to be properly managed. Since Requirement Identifications are defined to indicate whether a requirement has changed, the numbering should clearly reflect the type of change. If a change represents a revision to an existing requirement, including additions or modifications, the ".nn" version should be

updated. If the change represents a new requirement, a new requirement number "nnnnn" should be assigned, starting from the next number after the current last requirement, [E164-00-RQ-00400-00].

Motion: Negative is related and persuasive

By / 2nd: By: Albert Fuchigami / PEER Group Inc.
Second: Fahad Golra / Agileo Automation

Discussion: None

Vote: 10-Y 0-N

Motion: This Document failed TC Chapter review and will be returned to the TF for rework

By / 2nd: By: Albert Fuchigami / PEER Group Inc.
Second: Fahad Golra / Agileo Automation

Discussion: None

Vote: 10-Y 0-N

4.5 Document #7425, Line-Item Revision to SEMI E116-0324 Specification for Equipment Performance Tracking

4.5.1 Line Item #1: Establish Unique Well-Known Names

Motion: Line item(s) [1] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review

By / 2nd: By: Chris Maloney / Intel Corporation
Second: Brian Rubow / Cimetrix by PDF Solutions

Discussion: None

Vote: 9-Y 0-N

Attachment: AR - 7425

4.6 Document #7428, Revision to Add a New Subordinate Standard: Specification for Secure High-Speed SECS Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services

Reject Name: Motoki Miyamoto / Yokogawa Electric

Negative: This draft does not clearly define key requirements for secure TLS communication, including the use of SAN (Subject Alternative Names) and certificate validation rules.

Without these rules, host and equipment implementations may behave differently, leading to interoperability issues and a reduced expected level of security.

To achieve the goals of Secure-HSMS, the specification must explicitly define SAN requirements, certificate validation rules, etc.

Motion: Negative is related and persuasive

By / 2nd: By: Chris Maloney / Intel Corporation
Second: Brian Rubow / Cimetrix by PDF Solutions

Discussion: None

Vote: 12-Y 0-N

Motion: This Document failed TC Chapter review and will be returned to the TF for rework

By / 2nd: By: Chris Maloney / Intel Corporation
Second: Brian Rubow / Cimetrix by PDF Solutions

Discussion: None

Vote: 12-Y 0-N

5 Subcommittee and Task Force Reports

5.1 Advanced Backend Factory Integration (ABFI) Task Force

- Standards Development
- 7380
    - E142SubstrateMapDataReady
    - WKN Editorial changes
    - Other editorial changes
- 7381
    - E142 New Subordinate Document to align non-E142 wafer XY
    - Adding E142 Map Examples
    - Clarify Map XY Dimensions for Child Layouts

Attachment: ABFI TF Meeting_020926

5.2 Diagnostic Data Acquisition (DDA) Task Force

- EDA 'Core' Standards Update
    - Clarified that SEMI E125 could support state machines referenced in StateMachineInstance-only scenarios, and that state models defined at the equipment level (such as E30 Control State and E30 Process State) are referenced in StateMachineInstances.
- SEMI E164
    - Discussed using Well-Known Names (WKN) as a basis for metadata names to help with Data Collection Plan (DCP) re-useability. Need some further investigation.
    - Decided to retire existing RequirementIDs used by current SEMI E164 and create a new set of sequential RequirementIDs as part of the SEMI E164 rewrite. Look at providing reference material in the future outside of SEMI E164 to help with the transition.
    - Decided to state no restrictions in E164 about defining SEMI E120 nodes that have no data associated with it.

Attachment: DDA TF Report - February 2026_Rev 1.1

5.3 Graphical User Interface (GUI) Task Force

- Reviewed results of Ratification Ballot R6743C
- Reviewed timeline of document publication and SNARF
- Discussed some, but not all, of voter comments submitted for 6743C
- We propose to schedule interim TF meetings to continue discussing voter comments

Attachment: GUI TF Report - 2026-02-10

5.4 Digital Twins in Manufacturing Task Force

- Reviewed and adjusted SNARF
- Discussed latest input on DT attribute definition
- Agreed on next meeting time and agenda

Attachment: SEMI NA-ICC-DTM-TF Report 2026-02-11

5.5 GEM300 Task Force

- Adjudication of ballots
- Reviewed the E40 proposed SNARF
- Long discussion about E90 batch objects. Maybe getting closer to consensus, but some division still exists that might be difficult to reconcile.
- Long discussion about secure HSMS. Good alignment on the basic approach.

Attachment: SEMI NA-ICC-GEM300-TF Report Fall 2025

5.6 Computer & Device Security Task Force

- Leadership Changes
    - Ryan Bond resigned as co-leader
    - Michael Tanori (Intel) proposed new co-leader

Attachment: CDS TF Report 20260210

5.7 EDP Task Force

- New Activities
    - 7456, Revision to Add a New Subordinate Standard: Specification for Common Data for Deposition Components to Specification for Equipment Data Publication
        - Currently looking for deposition experts
    - 7457, Revision to Add a New Subordinate Standard: Specification for Common Data for Ion Implant Components to Specification for Equipment Data Publication

6 Next Meeting and Adjournment

The next meeting is scheduled for Wednesday, May 13, 2026, at ASMC. See http://www.semi.org/standards-events for the current list of events.

Adjournment: 1:49.

Respectfully submitted by:

Michelle Sun
Coordinator
SEMI North America
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Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Ballot Report - 7345A_v2	IC-Minutes-Oct-2025
Ballot Report - 7419	Liaison report_KR_InC_Dec2025
Ballot Report - 7425	JA_I&C_Liaison_2026_Jan_rev4
Required Meeting Elements March 2024	I&C_Staff_HQ Report Feb 2026 v3
ABFI TF Meeting_020926	SEMI NA-ICC-GEM300-TF Report Fall 2025
DDA TF Report - February 2026_Rev 1.1	GUI TF Report - 2026-02-10
SEMI NA-ICC-DTM-TF Report 2026-02-11	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Michelle Sun at the contact information above.